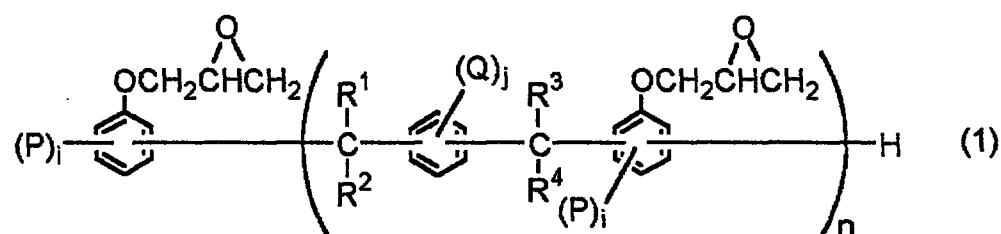


ABSTRACT OF THE DISCLOSURE

EPOXY RESIN COMPOSITION FOR ENCAPSULATING SEMICONDUCTOR, AND
RESIN-ENCAPSULATED TYPE SEMICONDUCTOR APPARATUS

Provided is an epoxy resin composition having low moisture absorption and excellent solder-crack resistance for encapsulating semiconductor comprising:

(A) an epoxy resin represented by formula (1)



(B) a curing agent having a phenolic hydroxyl group, and

(C) inorganic filler in an amount of 60 to 98% by weight based on the whole composition, and the epoxy resin composition is preferably used for a resin-encapsulated type semiconductor apparatus.